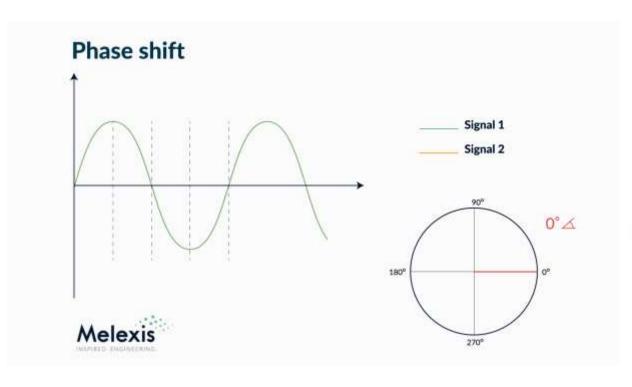
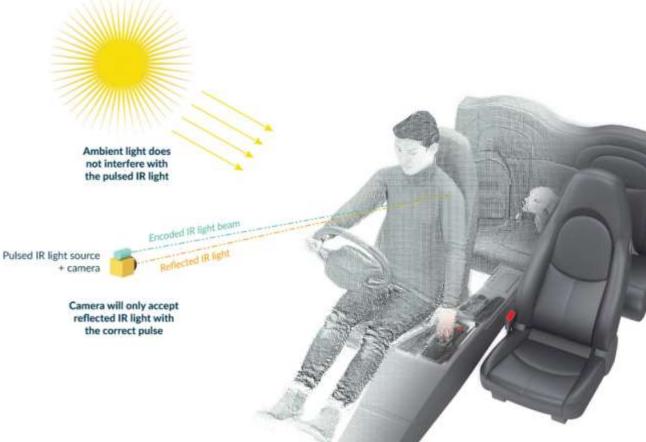


Introduction

Time-of-flight principle

ToF is a 3D sensing technology that is able to detect people and objects, their absolute position, movement and shape in 3 dimensions.

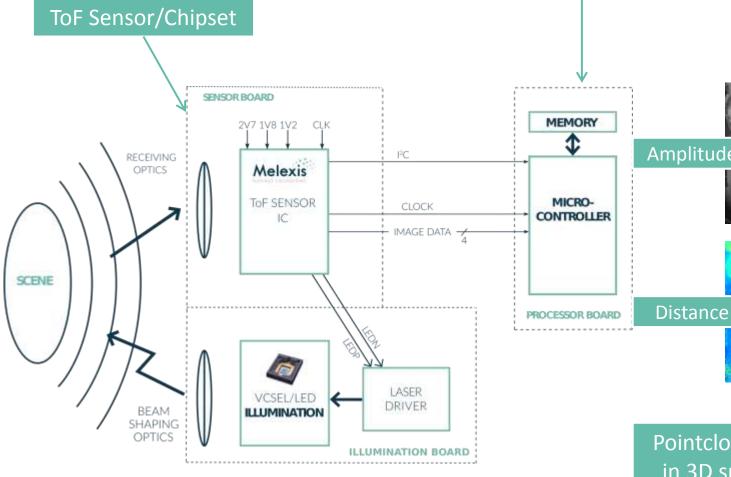




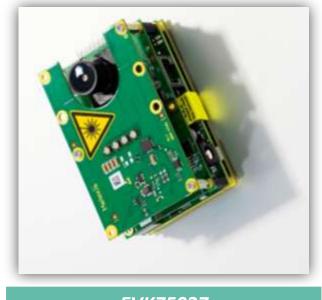
Introduction

System overview

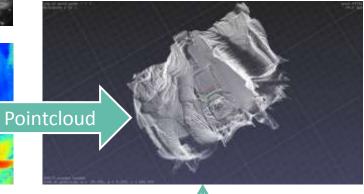
MCU takes care of processing the raw data into distance data







EVK75027 (Complete ToF camera system)



Pointcloud projecting every pixel information in 3D space taking into account the camera parameters



Products portfolio

Gen 1 QVGA ToF chipset

MLX75023 + MLX75123

Gen 2 QVGA ToF chipset

MLX75024 + MLX75123

Gen 3 VGA Integrated ToF sensor

MLX75027

Gen 3 QVGA Integrated ToF sensor

MLX75026

2017

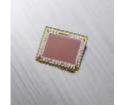
2018

2019

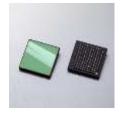
Q3 2020

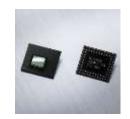












System cost optimization 850nm

Phase pre-processing Per-phase statistics & diagnostics

Performance improvement 850nm and 940nm

Embedded temp. sensor Selectable pixel gain X2 and x4 pixel binning CRC on metadata Single chip 850nm and 940 nm

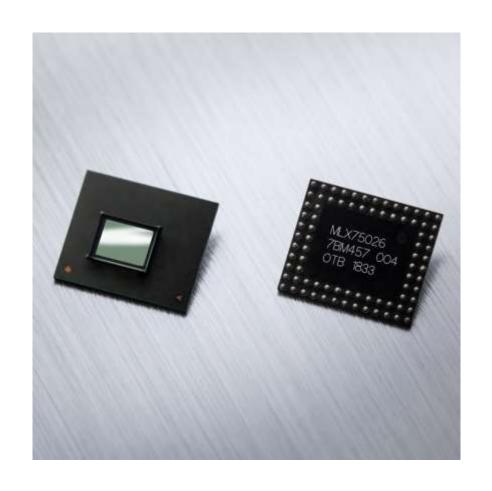
90nm BSI technology Up to 100MHz mod. Freq. Embedded temp. sensor Pixel binning CSI-2 Single chip 850nm and 940 nm

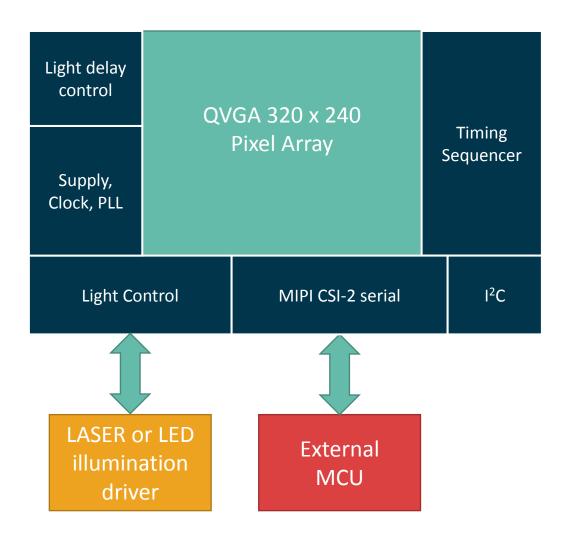
90nm BSI technology
Up to 100MHz mod. Freq.
Embedded temp. sensor
Pixel binning &CSI-2
Smaller footprint



MLX75026

Single chip QVGA ToF sensor



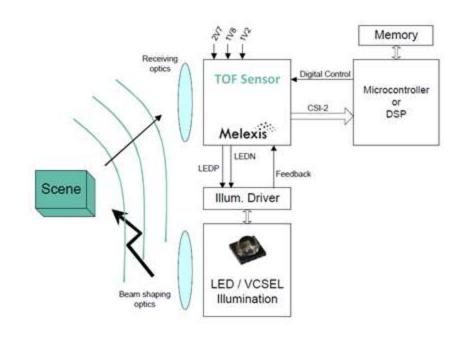




MLX75026

Single chip QVGA ToF sensor

- Fully integrated QVGA TOF Sensor (320 x 240)
- Modulation frequency up to 100 MHz
- Optimized for 940 nm illumination
- CSI-2 serial data output, MIPI D-PHY, 2 or 4 data lanes
- Region of interest (ROI), binning, Horizontal & vertical flip/mirror modes
- > 9.2 x 7.8 x 1.0 mm encapsulated BGA package with glass lid, double ARC coating
- Ambient temperature range -40° to +105°C





Key advantages of Gen3 QVGA

Against Melexis Gen2 chipset

Feature	Gen3 QVGA MLX75026	Gen2 QVGA MLX75024 & MLX75123BA	Advantages of Gen3 QVGA	
Resolution	320 x 240	320 x 240	Same resolution	
Pixel size	10x10um ²	15x15um ²		
External quantum efficiency (Typ)	51% @ 850 nm 28% @ 940 nm	22% @ 850 nm 13% @ 940 nm	Smaller pixel size (smaller footprint)Better optical performances	
optical filter or ARC	Double-sided ARC, 940nm IR BP filter optional	Double-sided ARC		
Sensor format	1/4"	1/3"	MLX75026 has a smaller sensor format → Smaller and Cheaper Lens	
Readout time	0.8 ms	0.96 ms		
Built-in temp. sensor	Tj accuracy +/	-5 °C absolute		
Max mod. frequency	Up to 100 MHz	Up to 40 MHz	Highest distance accuracy possible	
Data interface	CSI-2 D-Phy 2 or 4-Lane	12 bits parallel camera interface	Up to date communication interface	
Sensor footprint	9.2x7.8 mm = 71.8 mm ²	$(6.6x5.5)+(7x7) = 85.3 \text{ mm}^2$	MLX75026 has a very small package	
Power supply	2.7V, 1.8V and 1.2V	3V3, 2V, -3V3, 1V8	Simple and compact PSU architecture	
Power consumption	117 mW	384 mW	30 FPS, 250 μ s integration time, 40 MHz mod. freq.	



Key advantages of Gen3 QVGA

Comparison with Gen3 VGA

Feature	Gen3 QVGA MLX75026	Gen3 VGA MLX75027	Advantages of Gen3 QVGA	
Resolution	320 x 240	640 x 480	Smaller data size (25%) → Higher FPS	
Pixel size	10x10um²			
External quantum efficiency (Typ)	51% @ 850 nm 28% @ 940 nm		Same pixelsSame optical performances	
optical filter or ARC	Double-sided ARC, 940nm IR BP filter optional	Double-sided ARC	Possibility of integrated BP filter	
Sensor format	1/4"	1/2"	MLX75026 has a smaller sensor format → Smaller and Cheaper Lens	
Readout time	0.8 ms	1.5 ms		
Built-in temp. sensor	Tj accuracy +/	-5 °C absolute		
Max mod. frequency	Up to 1	00 MHz		
Data interface	CSI-2 D-Phy	2 or 4-Lane		
Sensor footprint	9.2 x 7.8 mm	14 x 14 mm	MLX75026 has a very small package	
Power supply	2.7V, 1.8V	' and 1.2V	Same PSU architecture	
Power consumption	120 mW 220 mW	221 mW 523mW	30 FPS, 250 μ s integration time, 60 MHz mod. freq. 60 FPS, 600 μ s integration time, 100 MHz mod. freq.	

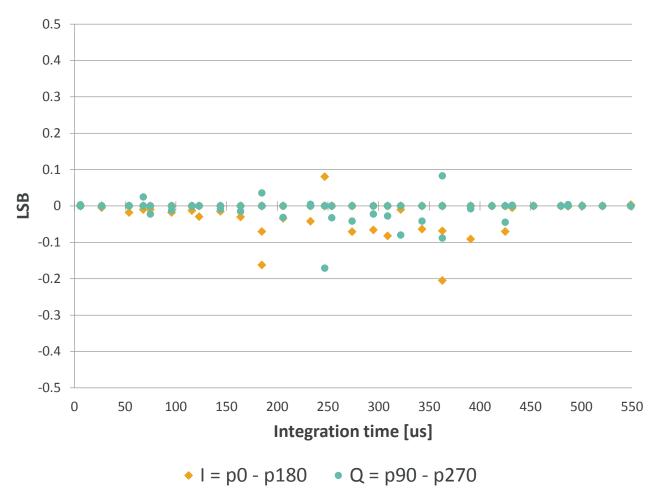
Compatible QVGA & VGA
Easy algorithm transfer between QVGA and VGA



Key advantages of Gen3 Pixels

Sunlight robustness

- Distance measurement accuracy is not affected by sunlight.
- Distance shift with constant light can be observed by monitoring I and Q values.
- Melexis Gen 3 ToF sensor shows no deviation (<0.2 LSBs) of the I, Q values under strong sunlight.



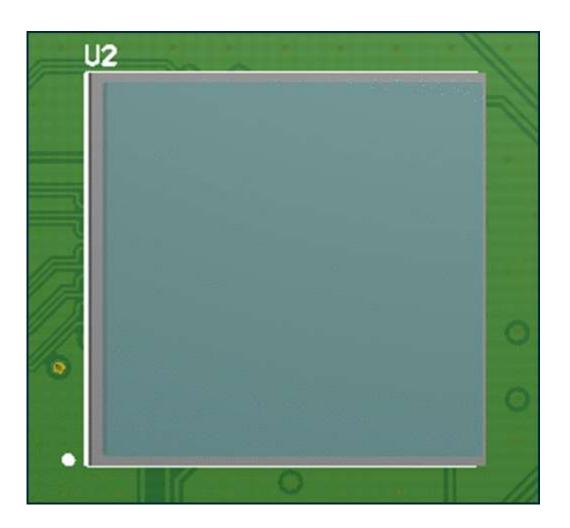




Migration from VGA to QVGA

Package size

- Decrease in package size :
 - MLX75027:
 - $14 \times 14 \text{ mm} = 196 \text{ mm}^2$
 - MLX75026:
 - $9.2 \times 7.8 \text{ mm} = 72 \text{ mm}^2$
- - Compact modules can benefit from the size reduction
 - Smaller & thus cheaper lenses can be used





Migration from VGA to QVGA

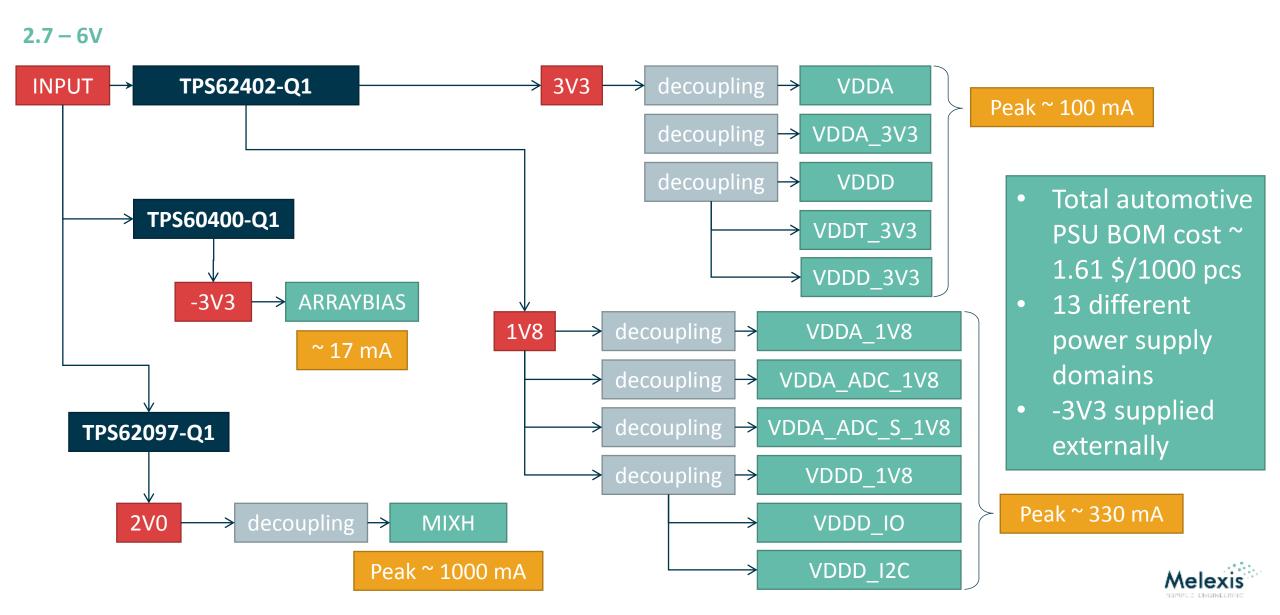
Registers updates

- MLX75026 & MLX75027 share similar registers structure :
 - Key application registers have the same addresses :
 - Integration time, Modulation frequency, Frame time, etc.
- Video output configuration, modes of operation and data output mode are identical.
- Register values needs to be adapted due to different HMAX values.
- Initialization maps are different.

Maximum software compatibility between Gen3 VGA & QVGA sensors.

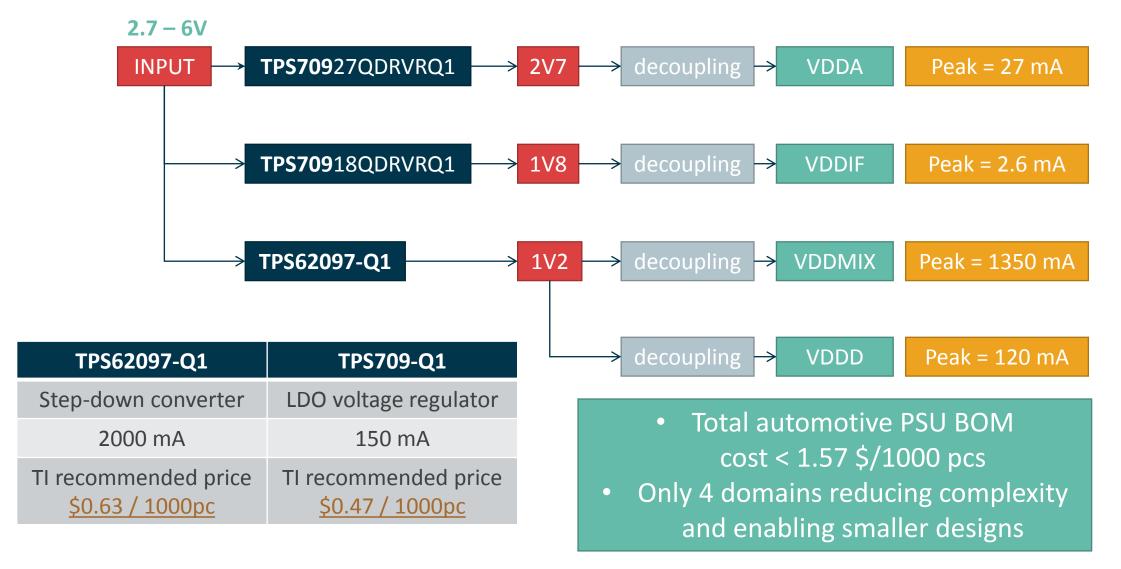


MLX75024 & MLX75123 - PSU Architecture



MLX75026 – PSU Architecture

Simple and cost effective





MLX75026 – Power consumption

Key parameters

- MLX75026 typical power consumption is ~ 99mW
- MLX75026 worst case power is ~ 163 mW (at low temperatures & typical conditions)
- Differences with Gen2 chipset :

 - Lower power consumption (~ 70 % less in typical application conditions)
- Differences with Gen3 VGA:
 - Lower power consumption (~ 50 % less in typical application conditions)

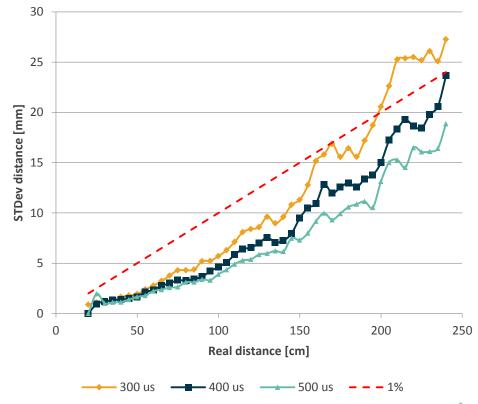


Tools

EVK75026-110-940-1

- EVK with automotive IU reference design
 - √ 1% distance precision with 2 VCSELs design (80 MHz modulation freq. & 97% reflectivity target).
 - ✓ Available with a 110° horizontal field-of view.
 - √ 940 nm automotive qualified VCSELs.
 - ✓ Illumination design collaboration with Lumentum (VCSEL supplier) and Lextar (package house).







ToF technology strong points

- Detection based on 2 simultaneous and different principles
 - ToF 3D output (distance) → segmentation based on <u>distance</u>
 - ToF 2D output (amplitude) → segmentation based on <u>scene contrast</u>
 + measure of distance confidence (precision)
- Distance measurement is insensitive to low contrast scenes
- Non intrusive in-car mounting
 - ToF camera can be hidden behind a dark cover
- Reported high algorithm detection performance
 - Because of accurate distance → accurate segmentation
- Reported robustness for intense sunlight
 - Sunlight does not impact distance accuracy
 - Sunlight invariance
- Reported low CPU load
 - For image processing algorithms/neural networks

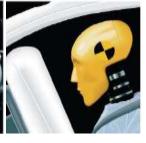


Automotive Use Cases

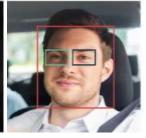














Comfort & UX

- Hand position detect
- Hand gestures
- Intuitive HMI, pointing finger
- Object detection, parcel classification
- Face and body recognition

Safety, NCAP, AD

- Driver monitoring, eye gaze/open/close..
- Driver activity detection
- Hands-on wheel
- Occupant classification, head& body pose
- Advanced seatbelt detection
- Child left behind

Security

- Anti-spoof (2D+3D based)face and body recognition
- Access control
- Secure authentication

Autonomous vehicles

- Blindspot detection
- Collision avoidance
- Autonomous parking
- Vehicle exterior cocoon
- Smart Access



Applications











Retail	Robotics	Smart cities	Logistics	Autonomous transport
People CountingShelf AnalysisInventory monitoring	 Collaborative robots Safety perimeter Human machine collaboration Behavioral prediction Workpiece identification 	Smart street lightingFree parking slotsAccess controlPeople counting	 Object identification and tracking Sizing and damage control 	 AGVs Path planning/SLAM Precision approach and docking Obstacle detection & collision avoidance

